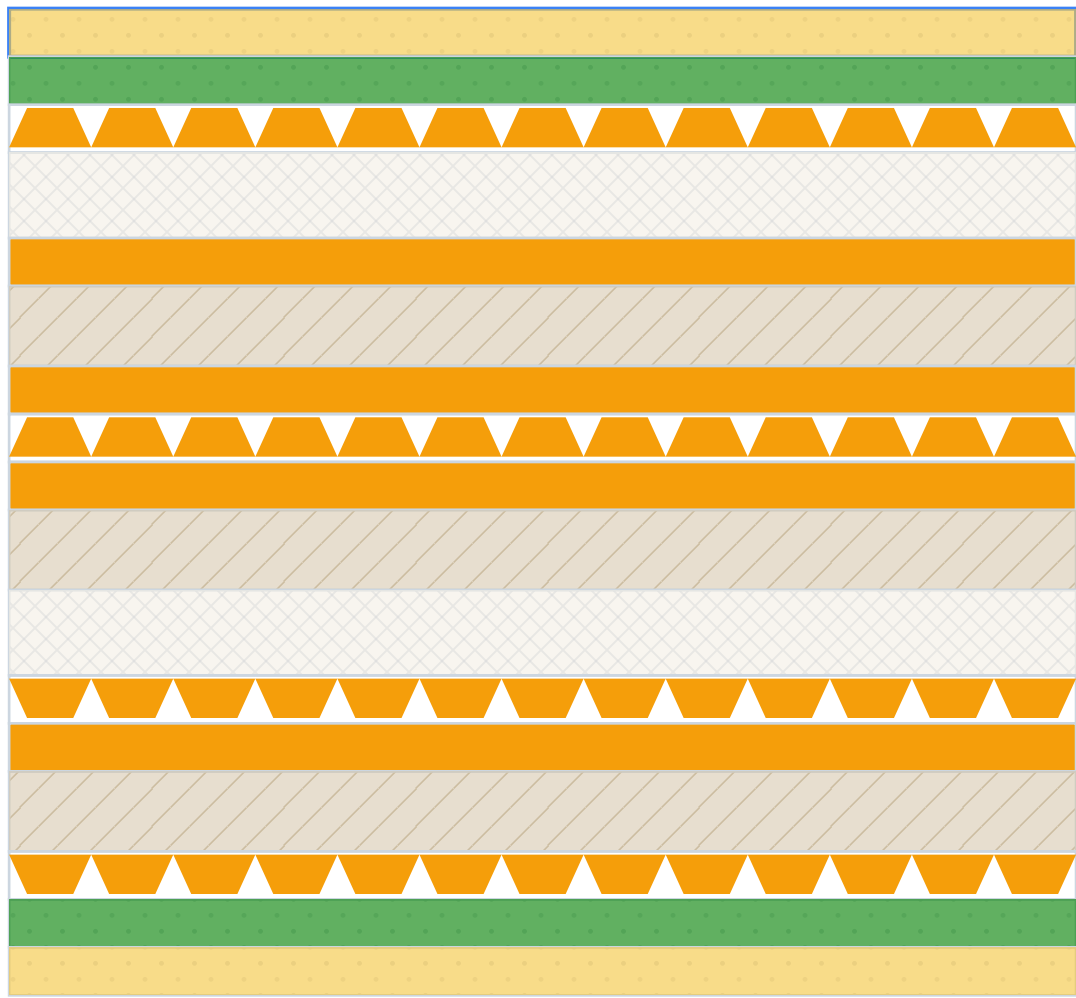


Top Surface Finish
 Top Solder Mask
L1 Signal 1
 Prepreg
L2 GND
 Core
L3 Power(VCC 1)
L4 Singnal 2
L5 GND
 Core
 Prepreg
Signal 3
Power(VCC 2)
 Core
L8 Signal 4
 Bottom Solder Mask
 Bottom Surface Finish



8 Layer Power-Enhanced

Spec	Type	Base Thickness	Processed Thickness	RC	DK
ENIG		0.005			
		0.020			
	Signal	0.018	0.018		
FR4 · 2116	Prepreg	0.13	0.1195	52%	4.3
	Plane	0.035	0.035		
FR4	Core	0.23	0.23		4.6
	Plane	0.035	0.035		
	Signal	0.035	0.035		
	Plane	0.035	0.035		
FR4	Core	0.23	0.23	43%	4.7
FR4 · 7628	Prepreg	0.196	0.175	43%	4.7
	Signal	0.035	0.035		
	Plane	0.035	0.035		
FR4	Core	0.23	0.23		4.5
	Signal	0.018	0.018		
		0.020			
ENIG		0.005			

Thickness After Lamination: 1.231 mm
 Finished PCB Thickness: 1.281 mm ±10%
 Inner layer Residual copper ratio: 70%